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Troubleshooting for Printed Board Manufacture and Assembly

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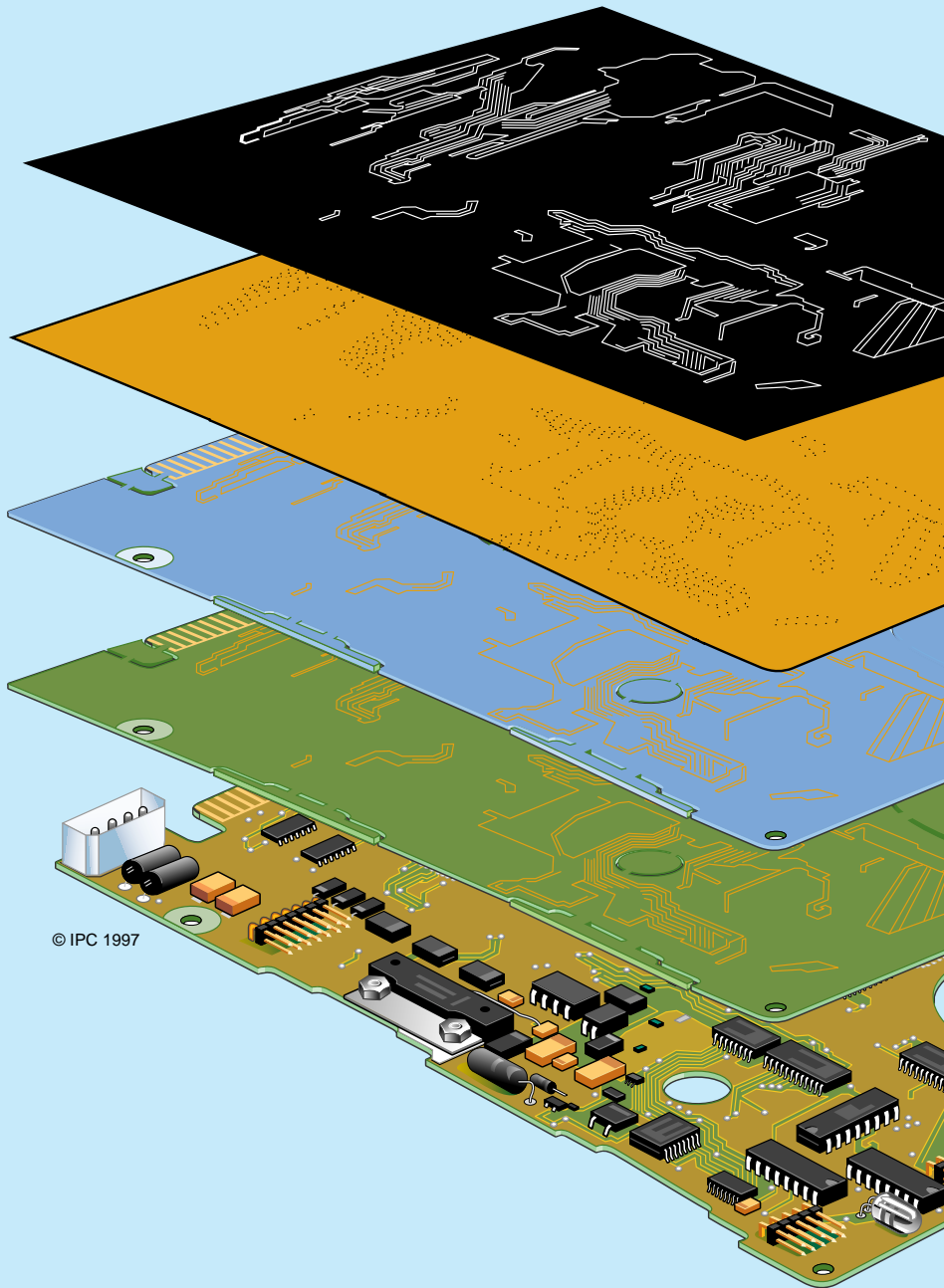


THE INSTITUTE FOR

INTERCONNECTING

AND PACKAGING

ELECTRONIC CIRCUITS



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Process Effects Handbook

Table of Contents

1.0 GENERAL INTRODUCTION	1	1.8.4 Calibration Program.....	9
1.1 PURPOSE AND FORMAT	1	1.8.5 Housekeeping.....	9
1.2 GUIDELINES FOR EFFECTIVE TROUBLESHOOTING AND PROCESS CONTROL	1	1.8.6 Proces Documentation and Procedures.....	9
1.2.1 Problem Identification and Statement	1	2.0 DESIGN AND DOCUMENTATION	1
1.2.2 Immediate Action Plans.....	2	2.1 DESIGN	1
1.2.3 Measurement System Evaluation	2	2.2 LAYOUT PROBLEMS	2
1.2.4 Parameter Diagnostics	2	2.3 ELECTRICAL	2
1.2.5 Parameter Analysis	2	2.4 MATERIAL	5
1.2.6 Corrective Action Plan	3	2.5 COMPONENTS	5
1.3 APPLICABLE DOCUMENTS	3	2.6 ASSEMBLY	6
1.3.1 IPC.....	3	2.6.1 Component Processing	6
1.3.2 Government.....	4	2.6.2 Moving Substrates	6
1.4 HANDLING	4	2.6.3 Assembly Process	7
1.4.1 Scratches	4	2.7 PRINTED BOARD FABRICATION	8
1.4.2 Bending or Flexing Panels	4	2.7.1 Holes	8
1.4.3 Fingerprints	4	2.7.2 Conductors	9
1.4.4 Storage.....	4	2.7.3 Construction	9
1.5 BAKING	5	2.8 BOARD PHYSICAL CHARACTERISTICS	9
1.5.1 General Problems Associated With Baking	5	2.9 DOCUMENTATION	9
1.5.2 Resin Curing	5	2.9.1 Printed Board Master Drawing	9
1.5.3 Stress Relief	5	2.9.2 Printed Board Assembly Documentation	12
1.5.4 Moisture Removal.....	6	2.10 INSPECTION AND TEST	12
1.5.5 Organic Coating Cure.....	6	2.11 RELIABILITY	13
1.6 RINSING	6	3.0 PHOTOTOOLING	1
1.6.1 Rinse Time	6	3.1 MATERIALS AND PROCESSES	1
1.6.2 Rinse Water Temperature.....	7	3.1.1 General	1
1.6.3 Agitation to Improve Rinsing.....	7	3.1.2 Diazo Film	1
1.6.4 Spray Rinsing.....	7	3.1.3 Silver Halide Film	4
1.6.5 Counterflow Rinsing	7	3.1.4 Glass - Silver Halide	7
1.6.6 Drip Times	7	3.1.5 Glass - Hard Surface Image on Glass	9
1.6.7 Special Rinse Techniques	8	3.2 ARTWORK	9
1.6.8 References	9	3.2.1 General	10
1.7 PACKAGING	9	3.2.2 Manually Prepared Artwork	11
1.8 MAINTENANCE	9	3.2.3 Photoplotter-Generated Artwork.....	13
1.8.1 Process Maintenance.....	9	3.2.4 Laser-Generated Artwork.....	13
1.8.2 Preventative Maintenance.....	9	3.2.5 Repair and Modification of Artwork.....	14
1.8.3 Corrective Maintenance	9		

3.3 PRODUCTION MASTER	14	5.4 SHEARING	11
3.3.1 Reduction Problems.....	14	5.4.1 Dimensional	11
3.3.2 Artwork Modifier Problems	15	5.4.2 Processing	11
3.3.3 Step-And-Repeat Problems.....	15	5.5 BEVELING	11
3.3.4 Coupons Versus End-Product Quality.....	16	5.5.1 Feature Quality	11
3.3.5 Measurement, Inspection and Touch-Up.....	19	5.5.2 Processing	12
3.3.6 Direct Imaging (Magnetic Tape) Problems.....	19	5.6 SCORING	12
3.4 WORKING PHOTOTOOL, PRODUCTION MASTER	19	5.6.1 Dimensional	13
3.4.1 Handling-Related Problems.....	19	5.6.2 Web Thickness and Web Location	13
3.4.2 Normalizing-Related Misregistration	20	5.6.3 Score Angle	13
3.4.3 Quality of Contact Prints.....	20	5.6.4 Surface Quality	13
3.4.4 Protective Coatings.....	21	5.7 LASER DRILLING	14
3.4.5 Pinning/Registration/Sandwiches	21	5.7.1 Dimensional	14
4.1 GENERAL	1	5.7.2 Hole Quality	14
4.1.1 Resins	1	5.8 WATER JET CUTTING/PROFILING	15
4.1.2 Reinforcements	1	5.8.1 Dimensional	15
4.1.3 Metal Foils.....	1	5.8.2 Feature Quality	15
4.2 PREPREG OR "B-STAGE"	1	5.8.3 Equipment	15
4.3 LAMINATE	2	6.0 HOLE PREPARATION	1
4.4 PROBLEMS ASSOCIATED WITH THE BASE MATERIALS	2	6.1 MECHANICAL	1
4.4.1 Material Identification	2	6.1.1 Deburring and Sanding.....	1
4.4.2 Dimensional Stability	3	6.1.2 Vapor Hone and Abrasive Blast.....	1
4.4.3 Mechanical Stability	3	6.2 CHEMICAL HOLE PREPARATION	2
4.4.4 Foreign Material / Inclusions	4	6.2.1 Resin Removal General.....	3
4.4.5 Metal Surface Defects	5	6.2.2 Alkaline Permanganate Desmearing/Etchback System	3
4.4.6 Chemical and Thermal Resistance.....	6	6.2.3 Sulfuric Acid Desmearing/Etchback System.....	4
4.4.7 Electrical	8	6.2.4 Chromic Acid Desmearing/Etchback System.....	5
5.0 MECHANICAL OPERATIONS	1	6.2.5 Reinforcement Removal, General	7
5.1 DRILLING	1	6.2.6 Ammonium Bifluoride/Hydrochloric Acid Reinforcement Removal	8
5.1.1 Dimensional	2	6.2.7 Hole Roughening	8
5.1.2 Hole Quality	4	6.3 PLASMA HOLE PREPARATION	9
5.1.3 Processing	7	6.3.1 Plasma Smear Removal.....	9
5.2 PUNCHING (PIERCE AND BLANK)	7	6.3.2 Side Effects	10
5.2.1 Dimensional	7	6.4 ELECTROCHEMICAL DEBURRING	10
5.2.2 Feature Quality	8	6.4.1 General.....	10
5.3 ROUTING	9	7.0 ELECTROLESS PROCESSES	1
5.3.1 Dimensional	9		
5.3.2 Feature Quality	10		
5.3.3 Processing	10		

7.1 HOLE METALLIZATION (CONDITIONING) (Includes Cleaner/Conditioner, Micro-Etch Solutions and Their Rinses)	1	9.2.3	Semi-Aqueous Resist.....	16
7.1.1 Bath Control.....	1	9.2.4	Solvent Resist	17
7.1.2 Hole Conditions	2	9.3 LIQUID PHOTORESIST		18
7.1.3 Surface Conditions.....	3	9.3.1 Common Problems of Liquid Photoresist.....		18
7.2 HOLE CATALYZATION (SENSITIZING) (Includes Predip, Catalyst, and Accelerator Baths and Their Rinses)	4	9.4 SCREEN PRINTED RESIST		21
7.2.1 Bath Control.....	4	9.4.1 Common Problems of Screen Printed Resist.....		21
7.2.2 Hole Conditions	4	9.5 ELECTROPHORETICALLY DEPOSITED PHOTORESIST		27
7.3 HOLE METALLIZATION (Copper Deposition) (Includes Electroless Copper Bath and Rinses)	5	9.6 LASER IMAGING OF PHOTORESIST		27
7.3.1 Bath Control	5	10.0 ELECTROPLATING		1
7.3.2 Hole Conditions	9	10.1 GENERAL		1
7.3.3 Surface Problems	12	10.2 COPPER ELECTROPLATING		4
7.4 HOLE METALLIZATION (REWORK)	13	10.2.1 General		4
7.5 SEMI-CONDUCTIVE COATINGS	13	10.2.2 Copper Sulfate		5
7.5.1 Palladium-Based	13	10.2.3 Pyrophosphate		11
7.5.2 Carbon Black Dispersion Process	14	10.2.4 Fluoborate		13
7.6 FULL BUILD ELECTROLESS COPPER	16	10.3 TIN-LEAD		14
7.6.1 Additive Processing	16	10.3.1 General		14
7.6.2 Semi-Additive Processing.....	18	10.3.2 Fluoborate-Based Baths		17
7.7 DIRECT METALLIZATION DURING DRILL OPERATION	19	10.3.3 Organic Sulfonic Acid (OSA) Based Baths.....		18
8.0 CLEANING PROCEDURES	1	10.3.4 High-Speed Tin-Lead Plating.....		19
8.1 MECHANICAL CLEANING PROCEDURES	1	10.3.5 High Throw Tin-Lead Plating		20
8.1.1 General	2	10.4 TIN		20
8.1.2 After Electroless Plating/Resist Application.....	3	10.4.1 General		20
8.1.3 Before Fusing.....	4	10.4.2 Bright Acid Sulfate Tin		20
8.2 CHEMICAL CLEANING PROCEDURES	4	10.5 NICKEL		22
8.2.1 General	4	10.5.1 General		22
8.2.2 Solder Conditioning Before Fusing	5	10.5.2 Sulfamate Nickel Baths		23
8.2.3 Cleaning After Fusing or Hot Air/Oil Level.....	6	10.5.3 Sulfate (Watts) Nickel		26
8.3 ELECTROCLEANING	6	10.6 GOLD PLATING		28
8.3.1 General	7	10.6.1 General		28
9.0 IMAGING	1	10.6.2 Gold Strike.....		29
9.1 GENERAL	1	10.6.3 Hard Gold		29
9.2 DRY FILM PHOTORESIST	1	10.6.4 Soft (bondable) Gold		31
9.2.1 Common Problems of Dry Film Photoresist	2			
9.2.2 Total Aqueous Resist	11			

10.7 CONTACT PLATING (TAB OR FINGER PLATING)	33	12.3.3 Etching	2
10.7.1 Preparation/Masking (Taping or Photoresist Application - Also see 9.2 and 16.4)	33	12.4 COPPER TREATMENT TO IMPROVE LAMINATE ADHESION	3
10.7.2 Tin-Lead Stripping.....	33	12.4.1 Double Treated Copper/Laminator's Oxide.....	3
10.7.3 Cleaning	34	12.4.2 Black or Red/Brown Oxide Coatings	4
10.7.4 Plating	34	12.4.3 Oxide Bath Control.....	5
10.8 MISCELLANEOUS PLATING SOLUTIONS	35	12.4.4 Oxide Post Treatment	6
10.8.1 Rhodium.....	35	12.4.5 Conveyorized Oxide Systems.....	7
10.8.2 Palladium.....	36	12.4.6 Delamination Relating to the Application of the Oxide Coating	8
10.8.3 Tin-Nickel Alloy Plating	36	13.0 LAMINATION	1
10.8.4 Palladium-Nickel.....	37	13.1 GENERAL	1
11.0 ETCHING	1	13.1.1 Misregistration	1
11.1 GENERAL	1	13.1.2 Blisters/Delamination and Interlaminar Adhesion	7
11.1.1 Equipment-Related Effects and Effects from Other Processes.....	1	13.1.3 Bowing/Twisting	7
11.2 CUPRIC CHLORIDE	4	13.1.4 Laminate Voids	7
11.2.1 Bath Control.....	4	13.1.5 Resin Starvation.....	7
11.2.2 Improper Etching	5	13.1.6 Panel/Board Thickness.....	7
11.3 ALKALINE (AMMONIACAL) ETCHANTS	6	13.1.7 Surface Imperfections	7
11.3.1 Bath Control.....	6	13.2 HANDLING	7
11.3.2 Improper Etching	7	13.2.1 Misregistration	8
11.4 PEROXIDE-SULFURIC ETCHANTS	9	13.2.2 Blisters/Delamination.....	8
11.4.1 Bath Control.....	9	13.2.3 Laminate Voids	8
11.4.2 Improper Etching	11	13.2.4 Surface Imperfections	8
11.5 FERRIC CHLORIDE	11	13.3 EQUIPMENT	8
11.5.1 Bath Control.....	11	13.3.1 Misregistration	9
11.5.2 Improper Etching	12	13.3.2 Blisters/Delamination.....	9
11.6 MISCELLANEOUS ETCHING SOLUTIONS	13	13.3.3 Laminate Voids	9
11.6.1 Ammonium or Sodium Persulfate.....	13	13.4 MATERIAL	9
12.0 INNERLAYER FABRICATION	1	13.4.1 Misregistration	9
12.1 GENERAL	1	13.4.2 Blisters/Delamination.....	10
12.1.1 Handling	1	13.4.3 Bow and Twist (Warped).....	10
12.1.2 Innerlayer Problems – General	1	13.4.4 Laminate Voids	10
12.2 PRINT AND ETCH INNERLAYERS	2	13.4.5 Resin Starvation.....	11
12.2.1 Cleaning	2	13.4.6 Panel Thickness.....	11
12.2.2 Resist Residue on Innerlayers	2	13.4.7 Surface Imperfections	11
12.2.3 Imaging	2	13.5 TOOLING	12
12.3 INNERLAYERS WITH BLIND AND/OR BURIED VIAS	2	13.5.1 Misregistration	12
12.3.1 Drilling	2	13.5.2 Bow and Twist (Warped).....	13
12.3.2 Plating	2	13.5.3 Surface Imperfections	13

13.6 MULTILAYER DESIGN	13	14.1.3 Hot Oil Reflow	3
13.6.1 Misregistration	13	14.1.4 Vapor Phase Fusing	4
13.6.2 Blisters/Delamination.....	14	14.2 SOLDER LEVELING	4
13.6.3 Bow and Twist (Warped)	14	14.2.1 Hot Air Leveling.....	4
13.6.4 Laminate Voids	14	14.2.2 Machine/Material Problems.....	5
13.6.5 Resin Starvation	14	14.3 IMMERSION COATINGS	6
13.6.6 Panel Thickness	15	14.3.1 Immersion Tin.....	6
13.7 INNERLAYER PREPARATION	15	14.3.2 Immersion Gold	7
13.7.1 Misregistration	15	14.3.3 Immersion Tin-Lead	8
13.7.2 Blisters/Delamination	16	14.4 ELECTROLESS COATINGS	9
13.7.3 Laminate Voids	18	14.4.1 Electroless Nickel	9
13.8 PREPREG (B-STAGE) PREPARATION	18	14.4.2 Electroless Tin.....	11
13.8.1 Blisters/Delamination.....	18	15.0 NON-METALLIC PROTECTIVE COATINGS	1
13.8.2 Laminate Voids	19	15.1 PERMANENT SOLDER RESIST	1
13.8.3 Panel Thickness	19	15.1.1 Screen Printable Solder Resists (Thermal and UV Cure)	1
13.9 COPPER FOIL PREPARATION	19	15.1.2 Dry Film Solder Resist	5
13.9.1 Blisters/Delamination.....	19	15.1.3 Liquid Photoimageable (LPI) Solder Resist	9
13.9.2 Surface Imperfections	19	15.2 TEMPORARY PROTECTIVE COATINGS	14
13.10 LAY UP	19	15.2.1 Inhibitor Coatings	14
13.10.1 Blisters/Delamination	19	15.2.2 Rosin-/Resin-Based Coatings (Prefluxes) ...	14
13.10.2 Bow and Twist (Warped)	20	15.2.3 Chromate Inhibitor Coatings	15
13.10.3 Panel Thickness	20	15.2.4 Copper Oxidation (Also see Section 12.4).....	15
13.10.4 Surface Imperfections	20	15.3 TEMPORARY SOLDER RESISTS	16
13.11 PRESSING	21	15.3.1 Tape	16
13.11.1 Misregistration	21	15.4 NOMENCLATURE (LEGEND) - NON-METALLIC MATERIALS	17
13.11.2 Blisters/Delamination.....	21	15.4.1 Screen-Printed.....	17
13.11.3 Bow and Twist (Warped)	22	15.4.2 Photoimageable	18
13.11.4 Laminate Voids	23	16.1 GENERAL	1
13.11.5 Resin Starvation	23	16.1.1 Electrostatic Discharge (ESD) Concerns	1
13.11.6 Panel Thickness	24	16.1.2 Component Leads	1
13.12 POST LAMINATION BAKE	25	16.1.3 Storage	1
13.12.1 Blisters/Delamination	25	16.2 COMPONENT PREPARATION	1
13.12.2 Bow and Twist (Warped).....	25	16.2.1 Pre-Tinning	1
13.12.3 Surface Imperfections	25	16.2.2 Pre-Forming	1
13.13 SUBSEQUENT PROCESSING	25	16.3 BOARD PREPARATION	2
13.13.1 Misregistration	25	16.3.1 Pre-Assembly Bake.....	2
13.13.2 Blisters/Delamination.....	26	16.4 COMPONENT INSERTION (THROUGH-HOLE) ..	3
13.13.3 Bow and Twist (Warped).....	26	16.4.1 Manual/Semi-Automatic	3
13.13.4 Voids in Plated Through Holes	26	16.4.2 Automatic Insertion (Through-Hole)	4
14.0 METALLIC PROTECTIVE COATINGS	1		
14.1 TIN-LEAD FUSING	1		
14.1.1 General	1		
14.1.2 Infra-red Fusing	3		

16.5 COMPONENT PLACEMENT SURFACE MOUNT	5	20.0 INSPECTION AND TEST	1
16.5.1 Adhesive Application	5	20.1 METHODS OF INSPECTION AND TEST	1
16.5.2 Solder Paste Application	7	20.1.1 Equipment	1
16.5.3 Component Placement (Surface Mount).....	19	20.1.2 Personnel	1
16.6 CHIP-ON-BOARD (Unpackaged Chip Components)	23	20.2 CLEANLINESS	1
16.6.1 Wire Bonding	23	20.2.1 Ionic contamination	1
16.6.2 TAB Bonding	23	20.2.2 Organic Contamination	2
17.1 GENERAL	1	20.3 ELECTRICAL TESTING	2
17.1.1 General Observed Conditions.....	1	20.3.1 Moisture and Insulation Resistance	2
17.2 SOLDERING MATERIALS	1	20.3.2 Insulation Resistance As Received	3
17.2.1 Adhesives (See Section 16.5.1, Adhesive Application).....	1	20.3.3 Dielectric Withstand	3
17.2.2 Solder Paste (Also see Section 16.5.2, Solder Paste Application)	2	20.3.4 Surface Insulation Resistance.....	3
17.2.3 Flux (See Section 17.4, Wave Soldering)	2	20.3.5 Electrical Continuity	3
17.2.4 Solder (See Section 17.4, Wave Soldering)	2	20.3.6 Isolation (Shorts).....	4
17.3 MANUAL (HAND) SOLDERING	2	20.4 VISUAL AND AUTOMATIC OPTICAL INSPECTION	4
17.4 WAVE SOLDERING	3	20.4.1 Visual Inspection.....	4
17.4.1 Equipment Related Problems	3	20.4.2 Automated Optical Inspection (AOI).....	6
17.4.2 Material/Prior Process Related Problems.....	5	20.5 THERMAL STRESS (Solder Float)	7
17.4.3 Design Related Problems	7	20.5.1 Coupon Conditioning and Thermal Stress	7
17.5 VAPOR PHASE SOLDERING	8	20.6 MICROSECTIONING	8
17.5.1 Equipment/Process Related Problems	8	20.6.1 Microsection Preparation.....	8
17.5.2 Material/Prior-Process Related Problems....	10	20.6.2 Microsection Etching.....	10
17.6 INFRARED/CONVECTION REFLOW SOLDERING	12	20.6.3 Microsection Evaluation	11
17.6.1 Equipment/Process Related Problems.....	12	20.7 OTHER TEST METHODS	12
17.6.2 Material/Prior-Process Related Problems....	14	20.7.1 Thermal Shock.....	12
18.1 CLEANING	1	20.7.2 Tensile Strength and Elongation	13
18.1.1 Solder Flux Removal.....	1	20.7.3 Bond Strength of Surface Mount Lands.....	13
18.1.2 Legend Ink Removal	5	20.7.4 Rework Simulation	14
18.1.3 Pre-encapsulation Cleaning	6	20.7.5 Gold Porosity Testing	14
19.0 POST SOLDERING PROCESSES	1	20.7.6 Copper Hole Wall Thickness Using Caviderm Type Resistance Measurements..	14
19.1 CONFORMAL COATING	1	20.7.7 Plating Thickness (Beta Backscatter).....	15
19.1.1 General Problems.....	3	20.7.8 Plating Thickness (X-Ray Fluorescence)....	15
19.1.2 Polyurethane Conformal Coatings	4	21.0 MODIFICATION, REWORK AND REPAIR	1
19.1.3 Silicone Conformal Coatings	5	21.1 TERMS AND DEFINITIONS	1
19.1.4 Paraxyllylene Conformal Coating	5	21.1.2 Rework	1
19.2 VARNISHING	6	21.1.3 Repair	1
19.3 POTTING AND CASTING	6	21.2 COMPONENT REMOVAL AND REPLACEMENT	1
		21.2.1 General Problems	1
		21.2.2 Conductive Heating Methods	2
		21.2.3 Convective Heating Methods	2